



JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO., LTD

SOT-23-3LK Plastic-Encapsulate Thyristors

CT401L 4Q TRIACs

MAIN CHARACTERISTICS

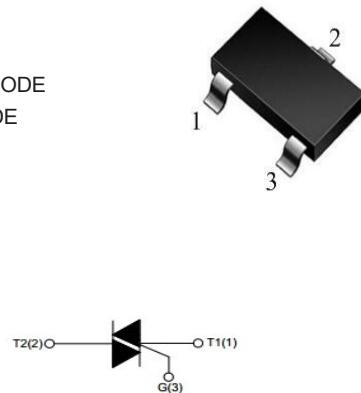
$I_{T(RMS)}$		1A
V_{DRM}/V_{RRM}	CT401L-600T/S	600V
	CT401L-800T/S	800V
V_{TM}		1.55V

FEATURES

- NPNPN 5-layer Structure TRIACs
- Mesa Glass Passivated Technology
- Multi Layers Metal Electrodes
- High Junction Temperature
- Good Commutation Performance

SOT-23-3LK

- 1.CATHODE
2.ANODE
3.GATE



APPLICATIONS

- Heater Control
- Motor Speed Controller
- Mixer

ABSOLUTE RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test condition		Value		Unit	
V_{DRM}/ V_{RRM}	Repetitive peak off-state voltage	$T_j=25^\circ\text{C}$	CT401L-600T/S	600		V	
			CT401L-800T/S	800		V	
$I_{T(RMS)}$	RMS on-state current	SOT-23-3LK($T_C \leq 60^\circ\text{C}$), Fig. 1,2		1		A	
I_{TSM}	Non repetitive surge peak on-state current	Full sine wave , $T_j(\text{init})=25^\circ\text{C}$, $t_p=20\text{ms}$; Fig. 3,5		10		A	
I^2t	I^2t value	$t_p=10\text{ms}$		1.28		A^2s	
dI_T/dt	Critical rate of rise of on-state current	$I_G=2*I_{GT}$, $t_r \leq 10\text{ns}$, $F=120\text{Hz}$, $T_j=125^\circ\text{C}$	$I - II - III$	50	$\text{A}/\mu\text{s}$		
			IV	10			
I_{GM}	Peak gate current	$t_p=20\mu\text{s}$, $T_j=125^\circ\text{C}$		2		A	
$P_{G(AV)}$	Average gate power	$T_j=125^\circ\text{C}$		0.5		W	
T_{STG}	Storage temperature			$-40 \sim +150$		$^\circ\text{C}$	
T_j	Operating junction temperature			$-40 \sim +125$			

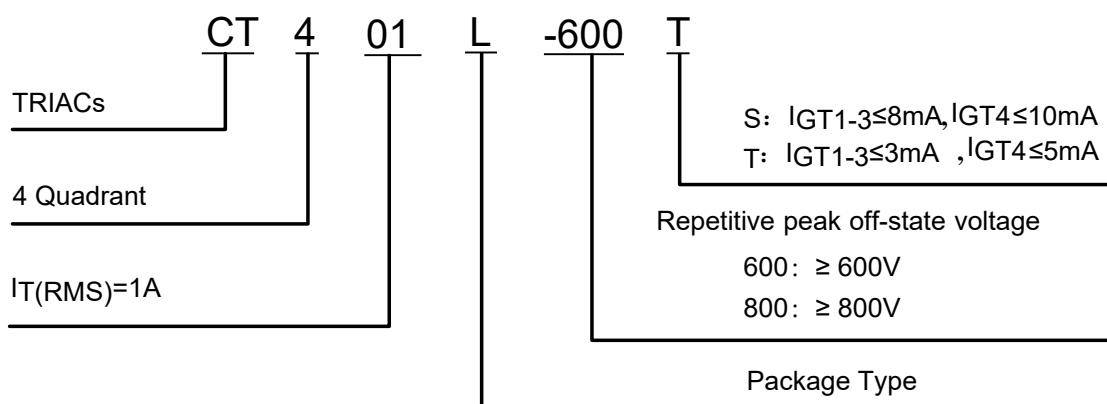
ELECTRICAL CHARACTERISTICS ($T_a=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test condition	Value		Unit	
			T	S		
I_{GT}	Gate trigger current	$V_D=12\text{V}$, $I_T=0.1\text{A}$, $T_j=25^\circ\text{C}$, Fig. 6	≤ 3	≤ 8	mA	
			≤ 5	≤ 10		
V_{GT}	Gate trigger voltage	I - II - III - IV	≤ 1.3		V	
V_{GD}	Non-triggering gate voltage	$V_D=V_{DRM}$, $T_j=125^\circ\text{C}$	≥ 0.2		V	
I_H	Holding current	$V_D=12\text{V}$, $I_{GT}=0.1\text{A}$, $T_j=25^\circ\text{C}$, Fig. 6	I - II - III - IV	≤ 5	≤ 5	mA
I_L	Latching current		I - III - IV	≤ 6	≤ 10	mA
			II	≤ 10	≤ 15	mA
dV_D/dt	Critical rate of rise of off-state	$V_D=67\%V_{DRM}$, Gate Open $T_j=125^\circ\text{C}$	≥ 20		≥ 50	V/ μ s
V_{TM}	On-state Voltage	$I_{TM}=1.5\text{A}$, $t_p=380\mu\text{s}$, Fig. 4	≤ 1.55		V	
I_{DRM} / I_{RRM}	Repetitive peak off-state current	$V_D=V_{DRM}/V_{RRM}$, $T_j=25^\circ\text{C}$	≤ 5	≤ 5	μA	
		$V_D=V_{DRM}/V_{RRM}$, $T_j=125^\circ\text{C}$	≤ 0.1	≤ 0.1	mA	

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th} (j-c)$	Junction to case (AC)	32	$^\circ\text{C/W}$
$R_{th} (j-a)$	Junction to ambient	400	$^\circ\text{C/W}$

PART NUMBER



CHARACTERISTICS CURVES

FIG.1: Maximum power dissipation versus RMS on-state current (full cycle)

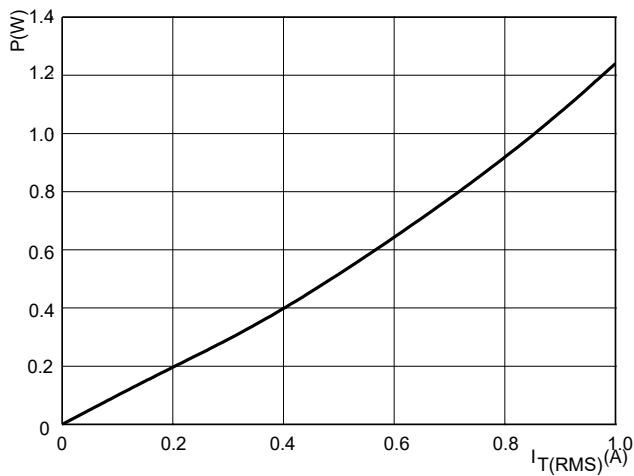


FIG.2: RMS on-state current versus case temperature (full cycle)

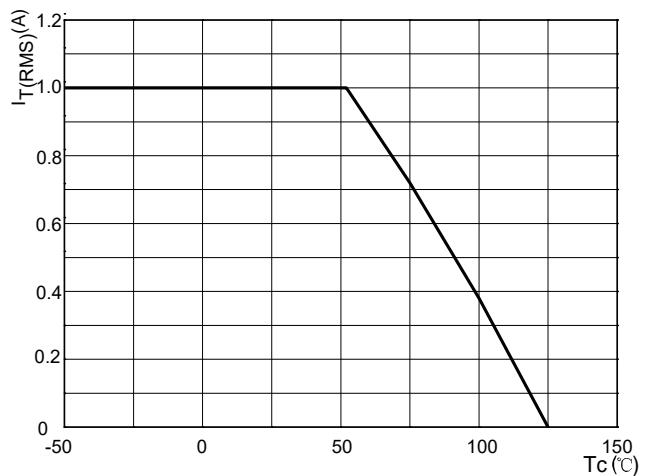


FIG.3: Surge peak on-state current versus number of cycles

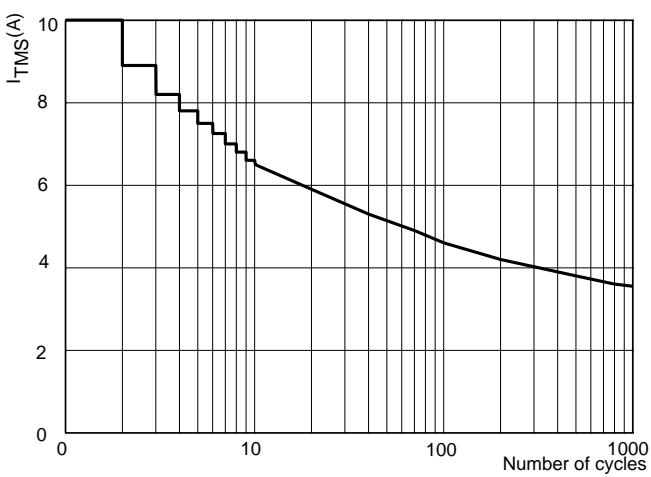


FIG.4: On-state characteristics (maximum values)

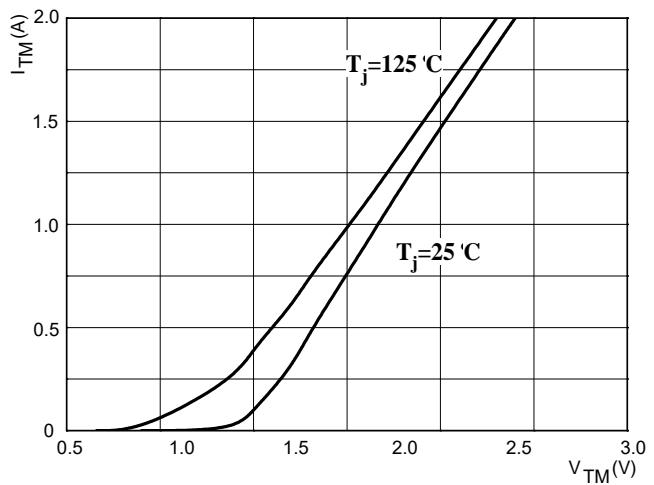


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 10\text{ms}$

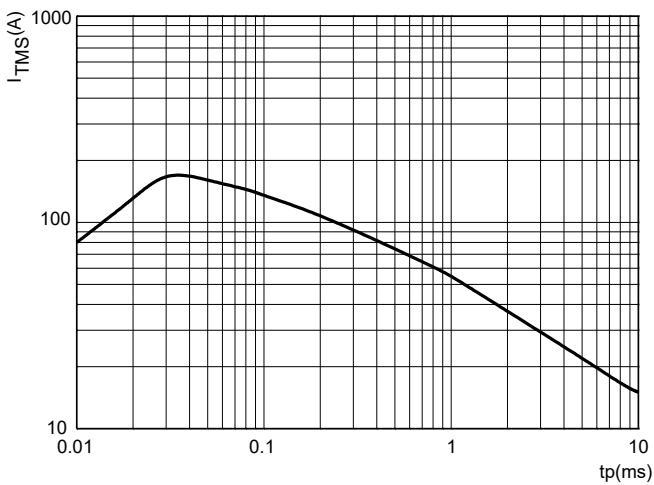
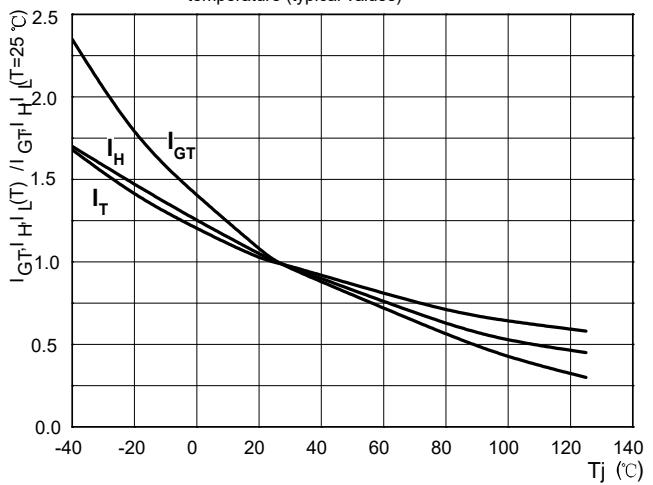
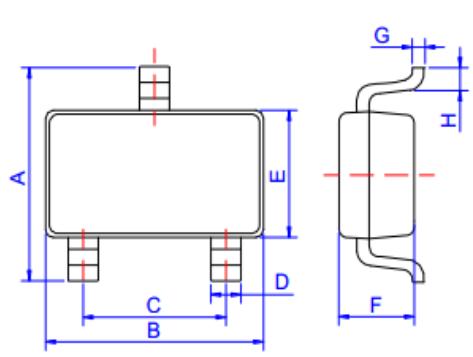


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature (typical values)



SOT-23-3LK PACKAGE OUTLINE DIMENSIONS



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.65		2.95	0.104		0.116
B		2.92			0.115	
C		1.90			0.075	
D	0.34		0.36	0.013		0.014
E		1.60			0.063	
F		1.17			0.046	
G		0.15			0.006	
H	0.25		0.55	0.010		0.022